AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. – 14. (Cancelled)

15. (Currently Amended) A method of manufacturing a circuit board, the circuit board including a substrate and having an output side terminal, the method comprising:

solder mounting first components within a pair of first regions on the substrate;

forming a band region between the pair of first regions including a second region, a third region having wiring patterns that join the first components together, and a longitudinal axis extending from the second region toward the output side terminal;

after mounting the first components, arranging an anisotropic conductive film within and extending along the longitudinal axis of ~~a~~ the band region of the substrate ~~located between the pair of first regions, the band region having a major axis and a minor axis with the major axis being greater than the minor axis~~;

arranging a second component on the anisotropic conductive film such that the anisotropic conductive film is disposed between the second component and the substrate; and

thermocompression-bonding the second component within ~~a~~ the second region ~~of~~ on the ~~band region~~ substrate ~~using a compression bonding head with the anisotropic conductive film disposed between the second component and the band region,~~;

~~wherein the band region extends toward the output side terminal such that the major axis of the band region is substantially perpendicular to the output side terminal~~.

16. (Previously Presented) A method of manufacturing a circuit board according to claim 15, wherein mounting of the first components on the substrate includes a reflow treatment.

17-20. (Cancelled)

21. (Currently Amended) A method of manufacturing a circuit board including an output side terminal disposed along an edge of the circuit board, the method comprising:

arranging a band region including a longitudinal axis extending toward the output side terminal on a surface of the circuit board between a pair of first regions~~, the band region having a major axis and a minor axis with the major axis being greater than the minor axis~~;

soldering a first component onto the circuit board in a first region located outside of the band region; and

following soldering of the first component to the first region, thermocompression-bonding a second component to the circuit board within the band region using an anisotropic conductive film and a compression bonding head where the band region is wider than the head~~;~~

~~wherein the band region extends toward the output side terminal such that the major axis of the band region is substantially perpendicular to the output side terminal~~.

22. (Previously Presented) The method of claim 21 wherein the thermocompression-bonding is performed with a heated compression bonding head, and

wherein the band region is selected to correspond generally to the areas over which the head travels to prevent impact of the head with the first component and isolating the first component from the heat generated by the head.

23. (Previously Presented) The method of claim 15, wherein the first components are selected from the group of passive and mechanical components, and the second component comprises a semiconductor device.

24. (Cancelled)

25. (Previously Presented) The method of claim 15, wherein alignment marks are provided outside the band region.

26. (Previously Presented) The method of claim 15, wherein the bonding region is selected by performing a solder reflow process.

27. (Cancelled)

28. (Previously Presented) The method of claim 23, wherein the second component is selected from the group of a power source IC and a power source LSI.

29. (Previously Presented) The method of claim 15, wherein the band region extends from one end of the substrate to another end of the substrate.

30. (Previously Presented) The method of claim 15, wherein the band region extends rectilinearly along the substrate.

31. (Previously Presented) The method of claim 15, further comprising:

forming wiring patterns on the substrate in the band region.

32. (Previously Presented) The method of claim 15, further comprising:

forming a dummy electrode at a position associated with the second component.

33-36. (Cancelled)

37. (Previously Presented) The method according to claim 21, wherein the band region is narrower than a surface of the circuit board.

38. (Currently Amended) A method according to claim 37, further comprising mounting other components in another region located outside of the band region, the other region ~~the second regions is~~ disposed on the surface of the circuit board on a side of the circuit board that opposed the first regions.

39. (Cancelled)

40. (New) The method according to claim 15, further comprising mounting another first component in another first region, the first region and the another first region disposed on opposing sides of the band region such that the band region extends between the first regions toward the output side terminal.

41. (New) The method according to claim 15, wherein thermocompression-bonding the second component includes using a compression bonding head having a width smaller than a width of the band region to avoid contact between the compression bonding head and the first components.